DATE: August 13, 2020

PCN #: 2478 - Advance Notice

PCN Title: Additional Wafer Source (GFAB) - Automotive

Dear Customer:

This is an advance announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this advance notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request within 30 days as well. Otherwise, samples may not be built prior to this change. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this Advance PCN.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team

ADVANCE NOTICE - PRODUCT CHANGE NOTICE PCN-2478 REV 1

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
August 11, 2020	Expected: December 31, 2020	Discrete - Automotive	Additional Wafer Source / Assembly BOM	2478

TITLE

Additional Wafer Source (GFAB)

DESCRIPTION OF CHANGE

This advance PCN is being issued to notify customers that in order to assure continuity of supply, Diodes is qualifying an additional internal wafer source located in Greenock, Scotland (GFAB), for automotive products.

Full electrical characterization and high reliability testing is ongoing on representative products to ensure there is no change to device functionality or electrical specifications in the datasheet.

In conjunction with adding the wafer source, several additional changes will be implemented on select part numbers to ensure continuity of supply, to standardize manufacturing processes, and to enhance manufacturability. This includes alignment of wafer fab and assembly bill of material (BOM), i.e. wafer process metal system, mold compound, die attach material, lead frame type, bond wire material and/or wire diameter.

Please note that date mentioned above is a best estimate derived from close coordination activities with our fab. Specific implementation dates may change depending on completion of various qualifications over the next few months. The final PCN is expected to be issued by December 1, 2020 once qualification has been completed.

IMPACT

Continuity of Supply. There will be no change to the Form, Fit or Function of products affected, unless specifically indicated.

No change in datasheet parameters and product performance.

PRODUCTS AFFECTED

Table 1: Additional Wafer Source (GFAB)
Table 2: Additional Wafer Source (GFAB) and Assembly BOM Change

WEB LINKS

Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/
For More Information Contact:	http://www.diodes.com/contacts.html
Data Sheet:	http://www.diodes.com/catalog

Table 1 - Additional Wafer Source (GFAB)

1N5819HWQ-7-F	B180BQ-13-F	B260Q-13-F	B350BQ-13-F	BAT64T5Q-13-F	PDS340Q-13
B1100BQ-13-F	B180Q-13-F	B270Q-13-F	B350Q-13-F	BAT64T5Q-7-F	PDS360Q-13
B1100Q-13-F	B190BQ-13-F	B280Q-13-F	B360AQ-13-F	PD3S120LQ-7	PDS4150Q-13
B120BQ-13-F	B190Q-13-F	B290Q-13-F	B360BQ-13-F	PD3S130HQ-7	PDS4200HQ-13
B120Q-13-F	B2100Q-13-F	B3100Q-13-F	B360Q-13-F	PD3S130LQ-7	PDS5100HQ-13
B130BQ-13-F	B220AQ-13-F	B320AQ-13-F	B370Q-13-F	PD3S140Q-7	PDS5100HQ-13D
B130Q-13-F	B220Q-13-F	B320BQ-13-F	B380Q-13-F	PD3S160Q-7	PDS5100Q-13D
B140BQ-13-F	B230AQ-13-F	B320Q-13-F	B390Q-13-F	PD3S220LQ-7	PDS540Q-13
B140Q-13-F	B230Q-13-F	B330AQ-13-F	B520CQ-13-F	PD3S230HQ-7	PDS560Q-13
B150BQ-13-F	B240AQ-13-F	B330BQ-13-F	B530CQ-13-F	PD3S230LQ-7	PDS760Q-13
B150Q-13-F	B240Q-13-F	B330Q-13-F	B540CQ-13-F	PDS1040Q-13	SDM160S1FQ-7
B160BQ-13-F	B250AQ-13-F	B340AQ-13-F	B550CQ-13-F	PDS3100Q-13	SDM20U30Q-7
B160Q-13-F	B250Q-13	B340BQ-13-F	B560CQ-13-F	PDS3100Q-7	SDM2100S1FQ-7
B170BQ-13-F	B250Q-13-F	B340Q-13-F	BAS40WQ-13-F	PDS3200Q-13	SDM40E20LAQ-7
B170Q-13-F	B260AQ-13-F	B350AQ-13-F	BAS40WQ-7-F		

Table 2 – Add GFAB as additional wafer source, and modify assembly BOM

B0520LWQ-7-F*	BAS70-04Q-7-F**	BAT1000Q-7-F	BAT54STQ-7-F**	DFLS140Q-7	ZHCS1000QTA
B0530WSQ-13-F**	BAS70-05Q-13-F**	BAT46WQ-7-F	BAT54SWQ-7-F*	DFLS160Q-7	ZHCS350QTA
B0530WSQ-7-F**	BAS70-05Q-7-F**	BAT54AQ-13*	BAT54TQ-7-F**	DFLS2100Q-7	ZHCS400QTA**
B0540WQ-7-F	BAS70-06Q-13-F**	BAT54AQ-7-F*	BAT54TWQ-7-F	DFLS230LQ-7	ZHCS400QTC**
B140HWQ-7	BAS70-06Q-7-F**	BAT54AWQ-7-F*	BAT54WQ-13-F*	DFLS230Q-7	ZHCS500QTA
BAS40-04Q-13-F	BAS70DW-04Q-13-F	BAT54AWQ-13-F	BAT54WQ-7-F*	DFLS240LQ-7	ZHCS500QTC
BAS40-04Q-7-F	BAS70DW-04Q-7-F	BAT54CQ-13*	BAT54WSQ-7-F*	DFLS240Q-7	ZHCS506QTA**
BAS40-05Q-13-F	BAS70DW-05Q-7-F*	BAT54CQ-7-F*	BAT760Q-7**	DFLS260Q-7	ZHCS750QTA
BAS40-05Q-7-F	BAS70Q-7-F	BAT54CWQ-7-F*	DFLS1100Q-7	SD103AWSQ-7-F**	ZLLS1000QTA
BAS40-06Q-13-F*	BAS70TWQ-13-F**	BAT54LPQ-7	DFLS1150Q-7	SD103BWSQ-7-F**	ZLLS2000QTA
BAS40-06Q-7-F	BAS70TWQ-7-F**	BAT54Q-13*	DFLS1200Q-7	SDM03U40Q-7**	ZLLS2000QTC
BAS40Q-13-F	BAS70W-04Q-7-F	BAT54Q-7-F*	DFLS120LQ-7	SDM1M40LP8Q-7**	ZLLS400QTA
BAS40Q-7-F*	BAS70W-05Q-7-F	BAT54SDWQ-7-F*	DFLS130LQ-7	SDM20U30LPQ-7*	ZLLS400QTC
BAS40TWQ-7-F*	BAS70W-06Q-7-F	BAT54SQ-13*	DFLS140LQ-7	SDM40E20LSQ-7-F	ZLLS500QTA
BAS70-04Q-13-F**	BAS70WQ-7-F	BAT54SQ-7-F*			

Note 1: “*” Also affected by Phenitec Wafer Manufacturing Site Change announced via PCN-2461

Note 2: “**” Change bond wire from Cu to Au